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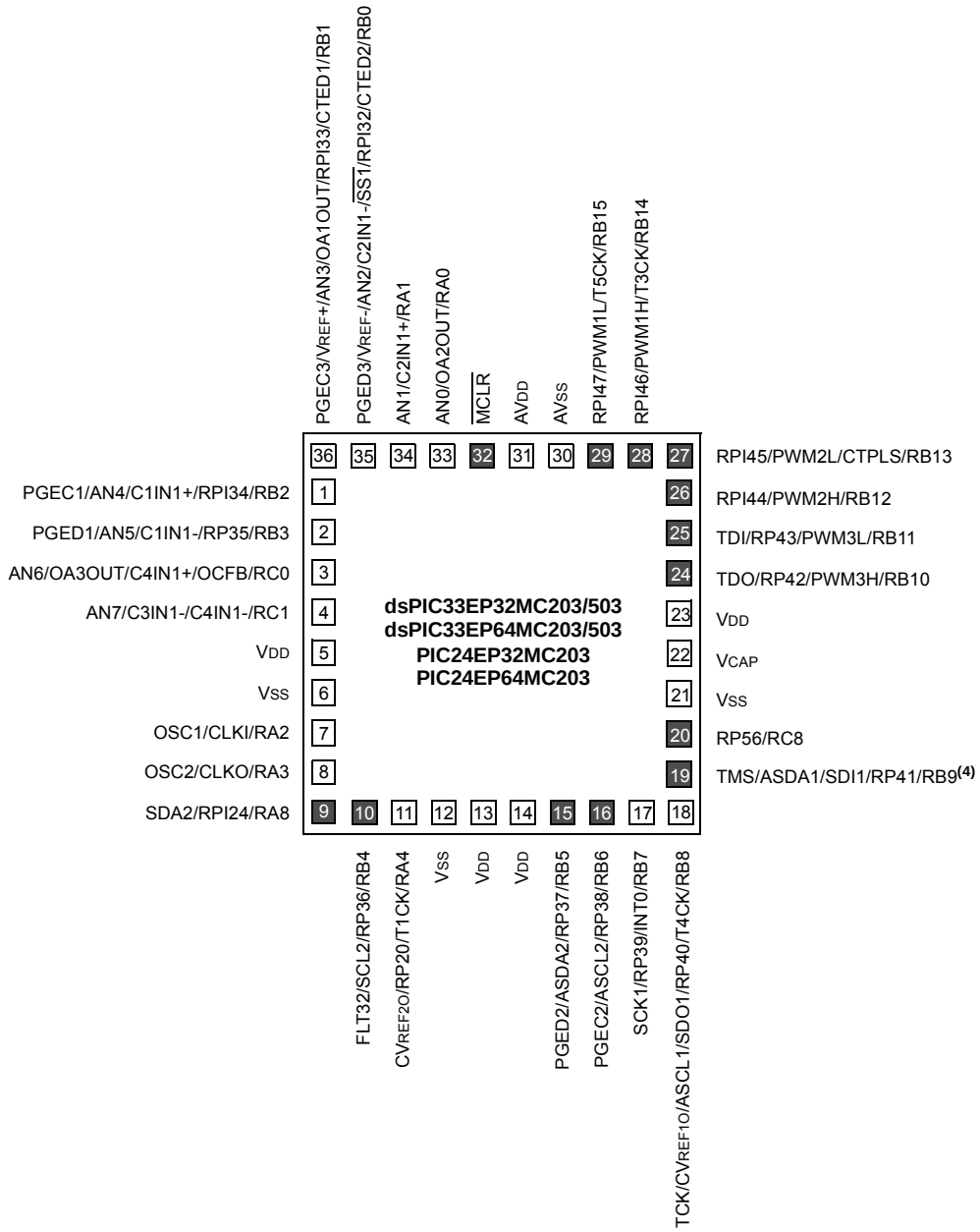
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep32mc202-i-ss

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 2-7: INTERLEAVED PFC

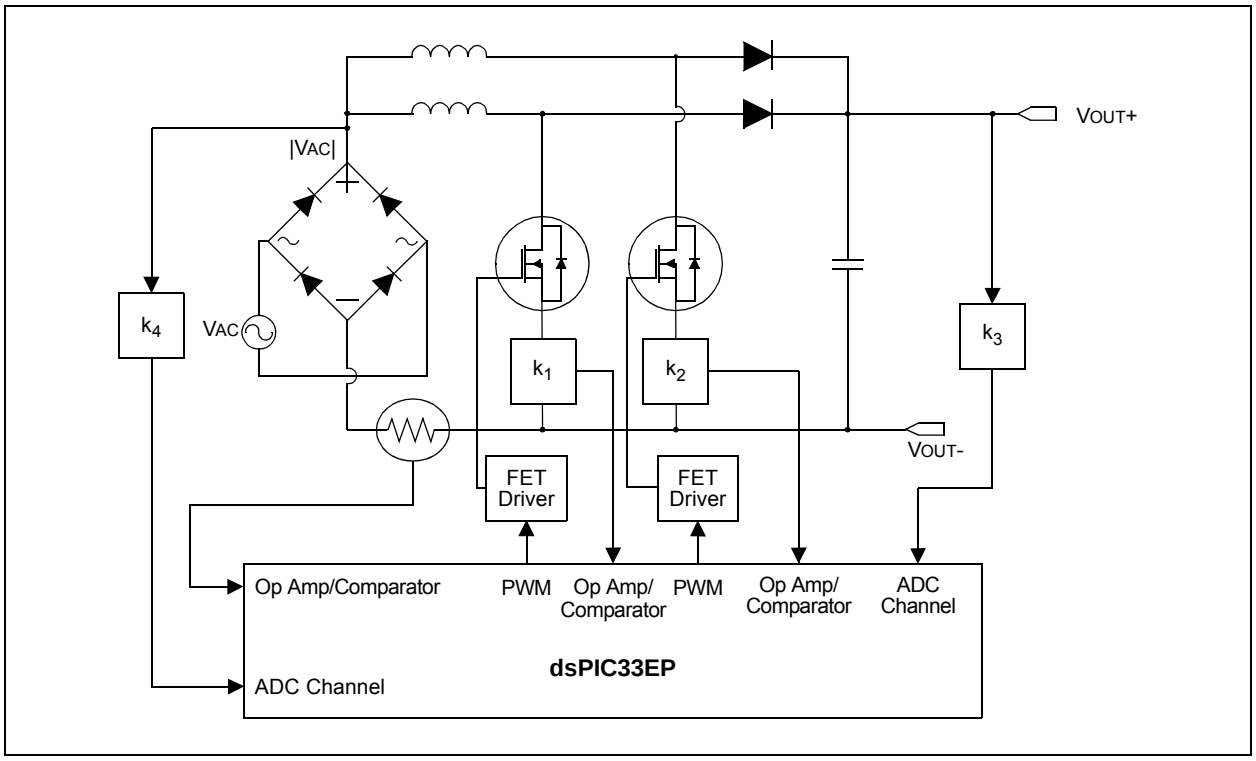


FIGURE 2-8: BEMF VOLTAGE MEASURED USING THE ADC MODULE

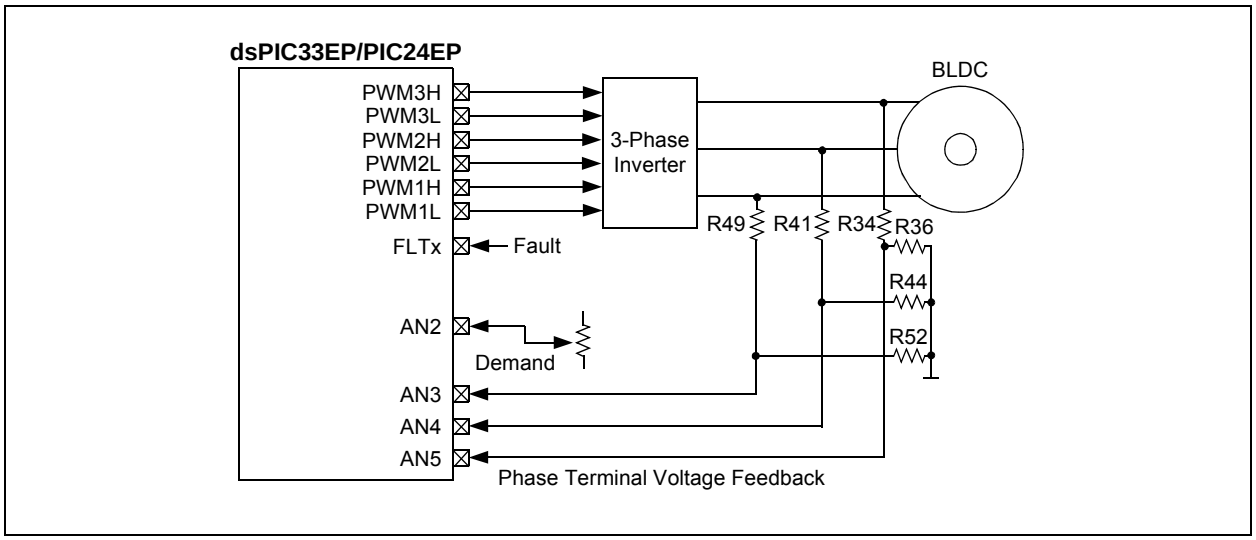
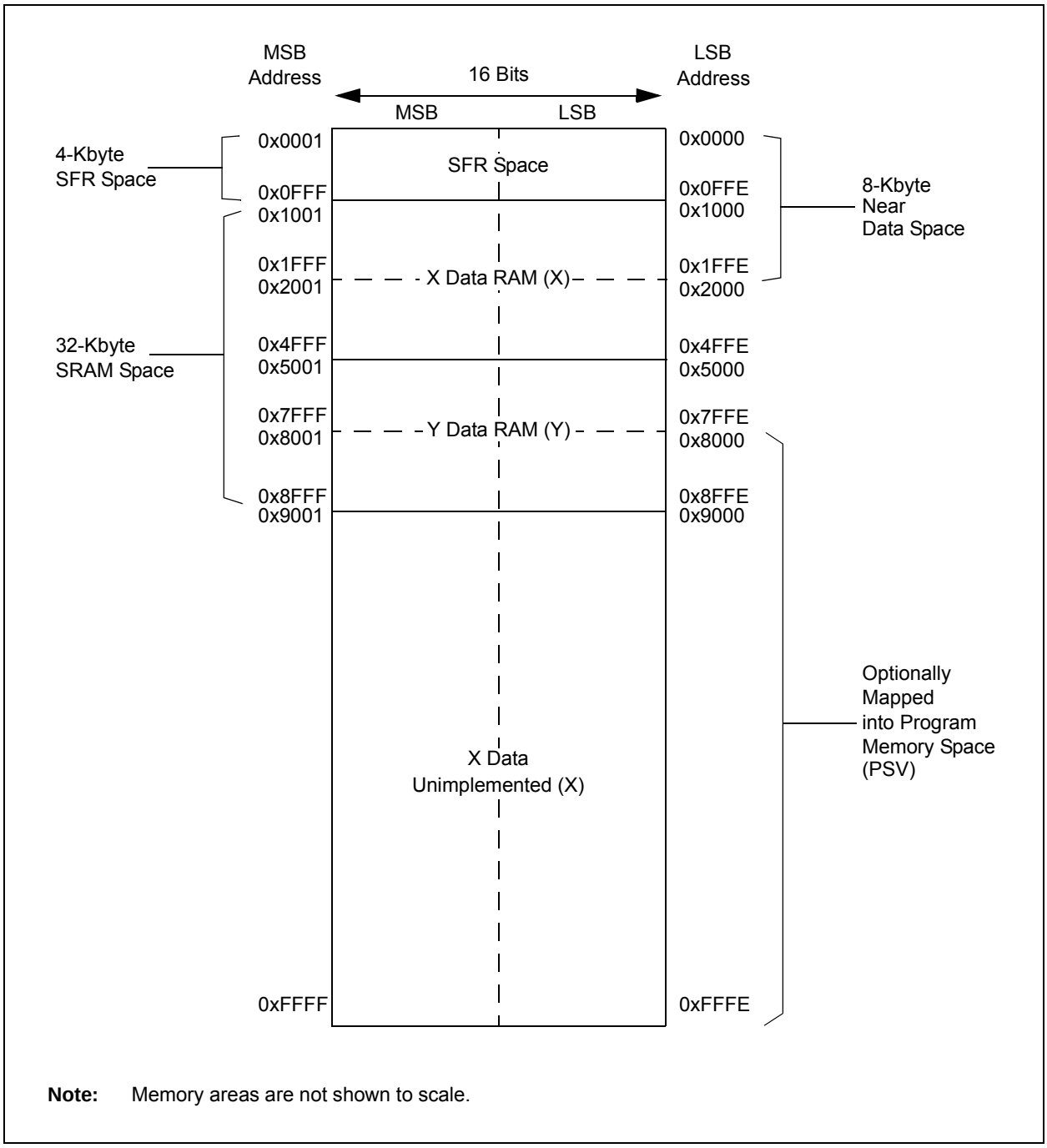


FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-49: PORTD REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISD	0E30	—	—	—	—	—	—	—	TRISD8	—	TRISD6	TRISD5	—	—	—	—	—	0160
PORTD	0E32	—	—	—	—	—	—	—	RD8	—	RD6	RD5	—	—	—	—	—	xxxx
LATD	0E34	—	—	—	—	—	—	—	LATD8	—	LATD6	LATD5	—	—	—	—	—	xxxx
ODCD	0E36	—	—	—	—	—	—	—	ODCD8	—	ODCD6	ODCD5	—	—	—	—	—	0000
CNEND	0E38	—	—	—	—	—	—	—	CNIED8	—	CNIED6	CNIED5	—	—	—	—	—	0000
CNPUD	0E3A	—	—	—	—	—	—	—	CNPUD8	—	CNPUD6	CNPUD5	—	—	—	—	—	0000
CNPDD	0E3C	—	—	—	—	—	—	—	CNPDD8	—	CNPDD6	CNPDD5	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-50: PORTE REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISE	0E40	TRISE15	TRISE14	TRISE13	TRISE12	—	—	—	—	—	—	—	—	—	—	—	—	F000
PORTE	0E42	RE15	RE14	RE13	RE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
LATE	0E44	LATE15	LATE14	LATE13	LATE12	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
ODCE	0E46	ODCE15	ODCE14	ODCE13	ODCE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNENE	0E48	CNIEE15	CNIEE14	CNIEE13	CNIEE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPUE	0E4A	CNPUE15	CNPUE14	CNPUE13	CNPUE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
CNPDE	0E4C	CNPDE15	CNPDE14	CNPDE13	CNPDE12	—	—	—	—	—	—	—	—	—	—	—	—	0000
ANSELE	0E4E	ANSE15	ANSE14	ANSE13	ANSE12	—	—	—	—	—	—	—	—	—	—	—	—	F000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-51: PORTF REGISTER MAP FOR PIC24EPXXXGP/MC206 AND dsPIC33EPXXXGP/MC206/506 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISF	0E50	—	—	—	—	—	—	—	—	—	—	—	—	—	—	TRISF1	TRISF0	0003
PORTF	0E52	—	—	—	—	—	—	—	—	—	—	—	—	—	—	RF1	RF0	xxxx
LATF	0E54	—	—	—	—	—	—	—	—	—	—	—	—	—	—	LATF1	LATF0	xxxx
ODCF	0E56	—	—	—	—	—	—	—	—	—	—	—	—	—	—	ODCF1	ODCF0	0000
CNENF	0E58	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNIEF1	CNIEF0	0000
CNPUF	0E5A	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPUF1	CNPUF0	0000
CNPDF	0E5C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CNPDF1	CNPDF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.2 EXTENDED X DATA SPACE

The lower portion of the base address space range, between 0x0000 and 0x7FFF, is always accessible regardless of the contents of the Data Space Page registers. It is indirectly addressable through the register indirect instructions. It can be regarded as being located in the default EDS Page 0 (i.e., EDS address range of 0x000000 to 0x007FFF with the base address bit, EA<15> = 0, for this address range). However, Page 0 cannot be accessed through the upper 32 Kbytes, 0x8000 to 0xFFFF, of base Data Space, in combination with DSRPAG = 0x000 or DSWPAG = 0x000. Consequently, DSRPAG and DSWPAG are initialized to 0x001 at Reset.

Note 1: DSxPAG should not be used to access Page 0. An EDS access with DSxPAG set to 0x000 will generate an address error trap.

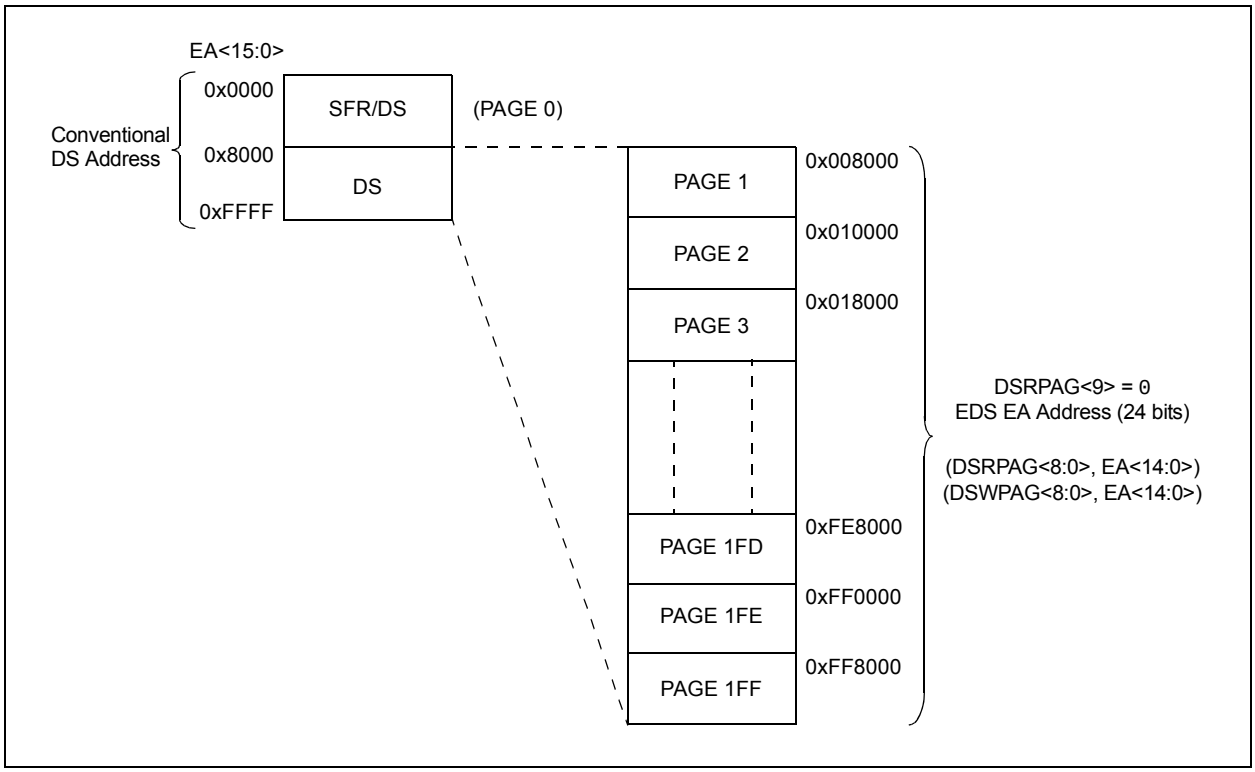
2: Clearing the DSxPAG in software has no effect.

The remaining pages, including both EDS and PSV pages, are only accessible using the DSRPAG or DSWPAG registers in combination with the upper 32 Kbytes, 0x8000 to 0xFFFF, of the base address, where base address bit, EA<15> = 1.

For example, when DSRPAG = 0x001 or DSWPAG = 0x001, accesses to the upper 32 Kbytes, 0x8000 to 0xFFFF, of the Data Space will map to the EDS address range of 0x008000 to 0x00FFFF. When DSRPAG = 0x002 or DSWPAG = 0x002, accesses to the upper 32 Kbytes of the Data Space will map to the EDS address range of 0x010000 to 0x017FFF and so on, as shown in the EDS memory map in Figure 4-17.

For more information on the PSV page access using Data Space Page registers, refer to the **"Program Space Visibility from Data Space"** section in **"Program Memory"** (DS70613) of the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 4-17: EDS MEMORY MAP



NOTES:

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER(2)

R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PENH	PENL	POLH	POLL	PMOD1(1)	PMOD0(1)	OVRENH	OVRENL
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PENH:** PWMxH Output Pin Ownership bit
1 = PWMx module controls PWMxH pin
0 = GPIO module controls PWMxH pin

bit 14 **PENL:** PWMxL Output Pin Ownership bit
1 = PWMx module controls PWMxL pin
0 = GPIO module controls PWMxL pin

bit 13 **POLH:** PWMxH Output Pin Polarity bit
1 = PWMxH pin is active-low
0 = PWMxH pin is active-high

bit 12 **POLL:** PWMxL Output Pin Polarity bit
1 = PWMxL pin is active-low
0 = PWMxL pin is active-high

bit 11-10 **PMOD<1:0>:** PWMx # I/O Pin Mode bits(1)
11 = Reserved; do not use
10 = PWMx I/O pin pair is in the Push-Pull Output mode
01 = PWMx I/O pin pair is in the Redundant Output mode
00 = PWMx I/O pin pair is in the Complementary Output mode

bit 9 **OVRENH:** Override Enable for PWMxH Pin bit
1 = OVRDAT<1> controls output on PWMxH pin
0 = PWMx generator controls PWMxH pin

bit 8 **OVRENL:** Override Enable for PWMxL Pin bit
1 = OVRDAT<0> controls output on PWMxL pin
0 = PWMx generator controls PWMxL pin

bit 7-6 **OVRDAT<1:0>:** Data for PWMxH, PWMxL Pins if Override is Enabled bits
If OVERENH = 1, PWMxH is driven to the state specified by OVRDAT<1>.
If OVERENL = 1, PWMxL is driven to the state specified by OVRDAT<0>.

bit 5-4 **FLTDAT<1:0>:** Data for PWMxH and PWMxL Pins if FLTMOD is Enabled bits
If Fault is active, PWMxH is driven to the state specified by FLTDAT<1>.
If Fault is active, PWMxL is driven to the state specified by FLTDAT<0>.

bit 3-2 **CLDAT<1:0>:** Data for PWMxH and PWMxL Pins if CLMOD is Enabled bits
If current-limit is active, PWMxH is driven to the state specified by CLDAT<1>.
If current-limit is active, PWMxL is driven to the state specified by CLDAT<0>.

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).
2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

19.1 I²C Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

19.1.1 KEY RESOURCES

- **"Inter-Integrated Circuit (I²C)"** (DS70330) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 20-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)
1 = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect
0 = Address Detect mode is disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)
1 = Receiver is Idle
0 = Receiver is active

bit 3 **PERR:** Parity Error Status bit (read-only)
1 = Parity error has been detected for the current character (character at the top of the receive FIFO)
0 = Parity error has not been detected

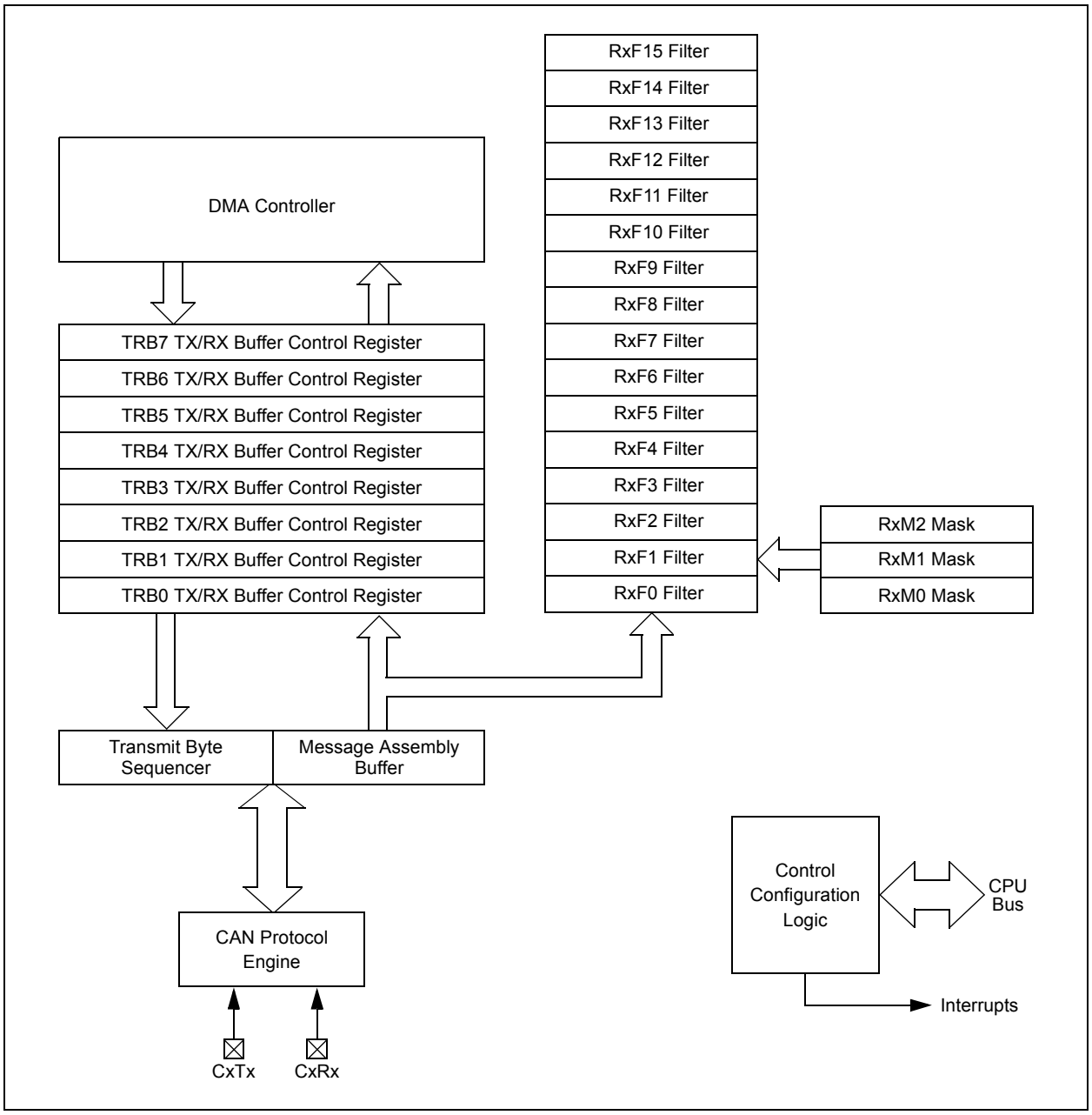
bit 2 **FERR:** Framing Error Status bit (read-only)
1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit (clear/read-only)
1 = Receive buffer has overflowed
0 = Receive buffer has not overflowed; clearing a previously set OERR bit (1 → 0 transition) resets the receiver buffer and the UxRSR to the empty state

bit 0 **URXDA:** UARTx Receive Buffer Data Available bit (read-only)
1 = Receive buffer has data, at least one more character can be read
0 = Receive buffer is empty

Note 1: Refer to the **"UART"** (DS70582) section in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UARTx module for transmit operation.

FIGURE 21-1: ECAN™ MODULE BLOCK DIAGRAM



REGISTER 21-13: CxBUFPNT2: ECANx FILTER 4-7 BUFFER POINTER REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP<3:0>				F6BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP<3:0>				F4BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F7BP<3:0>:** RX Buffer Mask for Filter 7 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F6BP<3:0>:** RX Buffer Mask for Filter 6 bits (same values as bits<15:12>)

bit 7-4 **F5BP<3:0>:** RX Buffer Mask for Filter 5 bits (same values as bits<15:12>)

bit 3-0 **F4BP<3:0>:** RX Buffer Mask for Filter 4 bits (same values as bits<15:12>)

REGISTER 21-14: CxBUFPNT3: ECANx FILTER 8-11 BUFFER POINTER REGISTER 3

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11BP<3:0>				F10BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F9BP<3:0>				F8BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **F11BP<3:0>:** RX Buffer Mask for Filter 11 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F10BP<3:0>:** RX Buffer Mask for Filter 10 bits (same values as bits<15:12>)

bit 7-4 **F9BP<3:0>:** RX Buffer Mask for Filter 9 bits (same values as bits<15:12>)

bit 3-0 **F8BP<3:0>:** RX Buffer Mask for Filter 8 bits (same values as bits<15:12>)

22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four Edge Input Trigger Sources
- Polarity Control for Each Edge Source
- Control of Edge Sequence
- Control of Response to Edges
- Precise Time Measurement Resolution of 1 ns
- Accurate Current Source Suitable for Capacitive Measurement
- On-Chip Temperature Measurement using a Built-in Diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors.The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

REGISTER 22-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge Sampling Mode Selection bit
1 = Edge 1 is edge-sensitive
0 = Edge 1 is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1xxx = Reserved
01xx = Reserved
0011 = CTED1 pin
0010 = CTED2 pin
0001 = OC1 module
0000 = Timer1 module

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the edge source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the edge source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 7 **EDG2MOD:** Edge 2 Edge Sampling Mode Selection bit
1 = Edge 2 is edge-sensitive
0 = Edge 2 is level-sensitive

bit 6 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 is programmed for a positive edge response
0 = Edge 2 is programmed for a negative edge response

bit 5-2 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = Reserved
01xx = Reserved
0100 = CMP1 module
0011 = CTED2 pin
0010 = CTED1 pin
0001 = OC1 module
0000 = IC1 module

bit 1-0 **Unimplemented:** Read as '0'

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample MUXA bit

In 12-bit mode (AD21B = 1), CH123SA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER (CONTINUED)

bit 3 **ABEN:** AND Gate B Input Enable bit
1 = MBI is connected to AND gate
0 = MBI is not connected to AND gate

bit 2 **ABNEN:** AND Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to AND gate
0 = Inverted MBI is not connected to AND gate

bit 1 **AAEN:** AND Gate A Input Enable bit
1 = MAI is connected to AND gate
0 = MAI is not connected to AND gate

bit 0 **AANEN:** AND Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to AND gate
0 = Inverted MAI is not connected to AND gate

TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

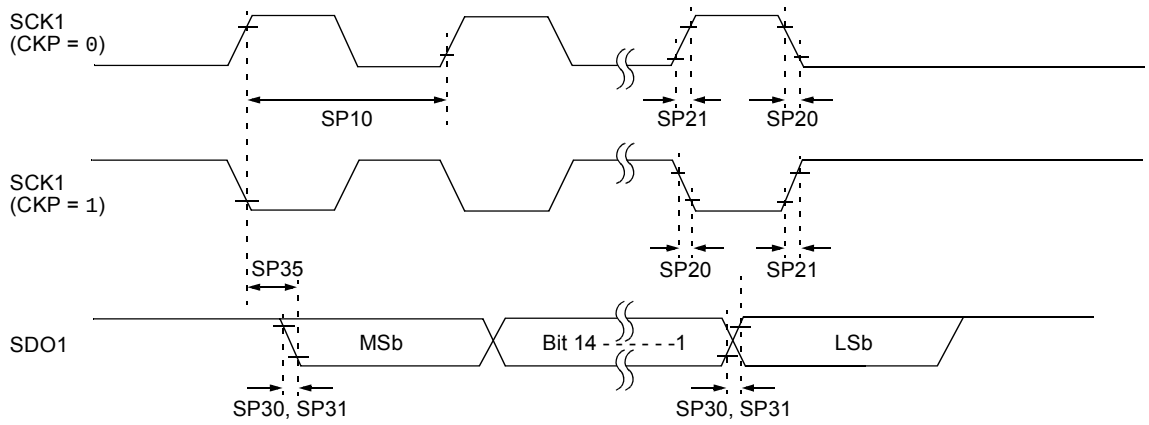
3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-41: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-42	—	—	0,1	0,1	0,1
10 MHz	—	Table 30-43	—	1	0,1	1
10 MHz	—	Table 30-44	—	0	0,1	1
15 MHz	—	—	Table 30-45	1	0	0
11 MHz	—	—	Table 30-46	1	1	0
15 MHz	—	—	Table 30-47	0	1	0
11 MHz	—	—	Table 30-48	0	0	0

FIGURE 30-22: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-49: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(4)**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG +2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 2)	—	µs	
			400 kHz mode	TCY/2 (BRG + 2)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 2)	—	µs	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(2)	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 3)**

Note 1: BRG is the value of the I^2C™ Baud Rate Generator. Refer to **"Inter-Integrated Circuit (I^2C™)"** (DS70330) in the "*dsPIC33/PIC24 Family Reference Manual*". Please see the Microchip web site for the latest family reference manual sections.

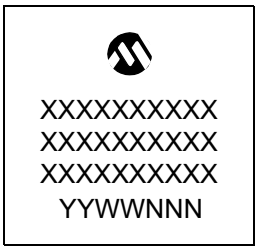
2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

4: These parameters are characterized, but not tested in manufacturing.

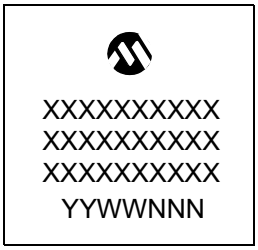
33.1 Package Marking Information (Continued)

36-Lead VTLA (TLA)



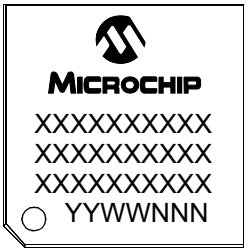
Example

44-Lead VTLA (TLA)



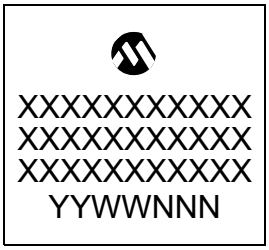
Example

44-Lead TQFP



Example

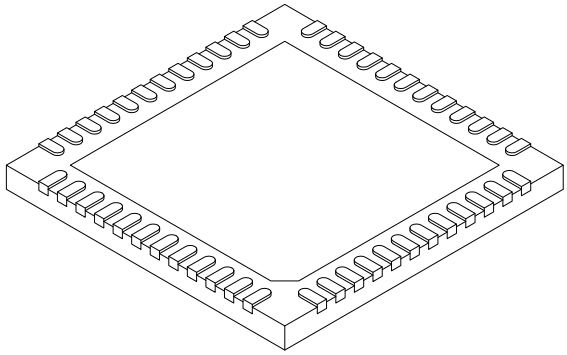
44-Lead QFN (8x8x0.9 mm)



Example

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2